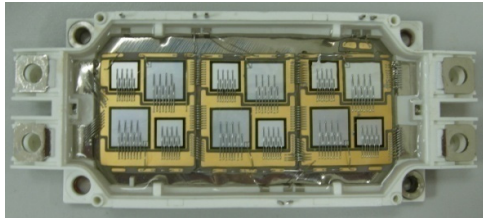


Data Sheet – IGBT Module

DESCRIPTION

Lingsen's IGBT module is a DBC based, silicon dielectric gel encapsulated package. It is available in half-bridge circuit structure or can be customized to individual or automobile customer needs.



It is widely used for motor drives, commercial agriculture vehicles and UPS system.

APPLICATIONS

- Motor drive and inverter.
- UPS and DC power.
- EV/HEV charger

FEATURES

- Meet automobile or industrial material level requirements.
- Fast switching speed.
- Low conduction loss
- Soft turn-off performance.
- High isolation voltage.

SPECIFICATIONS

DBC: 0.635 or 0.38 core material
 Die Attach: SAC305 or equilibrium
 Alumina Wire: 99.99%Al.
 Dielectric material: SYLGARD 527
 Base plate: Copper with Nickel plating
 Marking: Laser.

PACKAGE AVAILABILITY

Package Size (mm)	Vces(min.) (V)	Ic (A)
62x122	600	450

RELIABILITY

High temp. storage	150°C,	1000 hrs.
Temp. cycling	-40/125°C,	1000 cycles
Autoclave	121°C/100%RH,	96 hrs.

Data Sheet – IGBT Module

THERMAL PERFORMANCE

Package	Body size (mm)	Pad size (mm)	Die size (mm)	Thermal Performance ψ_{ja} ($^{\circ}\text{C}/\text{W}$)
	62x122		IGBT 13.5X13.5/Diode 10x10	$R_{jc} < 0.3$

ELECTRICAL PERFORMANCE

Package	Body size (mm)	Pad size (mm)	Frequency (MHz)	Self inductance (nH)	Self capacitance (pF)	Resistance (mohm)

CROSS-SECTION

